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CHINA**<sup>®</sup>

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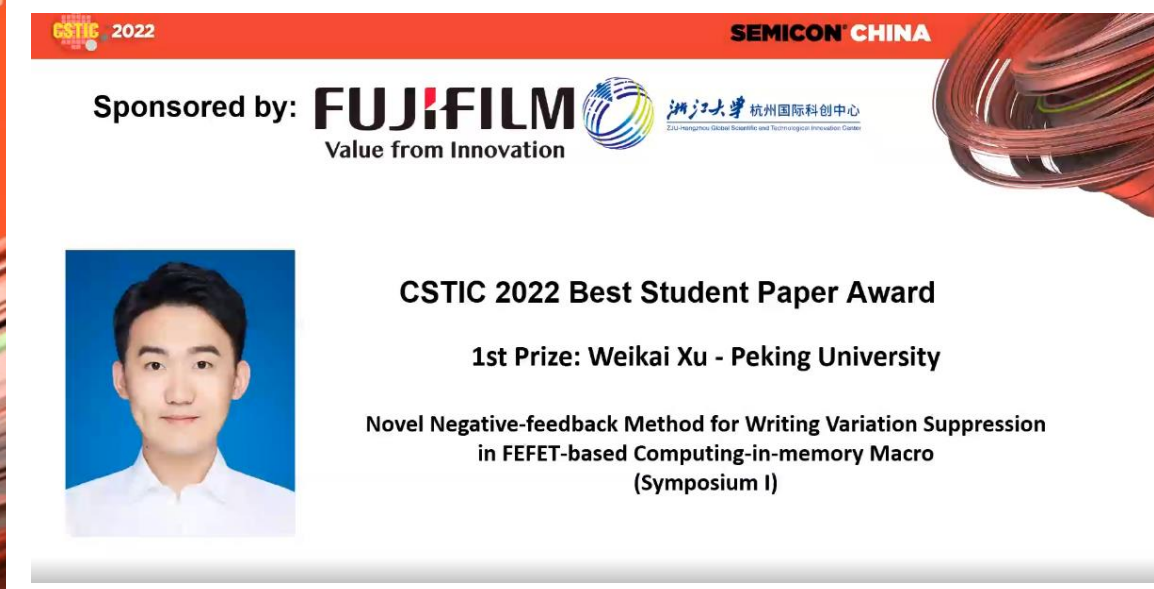
# China Semiconductor Technology International Conference (CSTIC) 2022 Summary

June 14-July 12, 2022



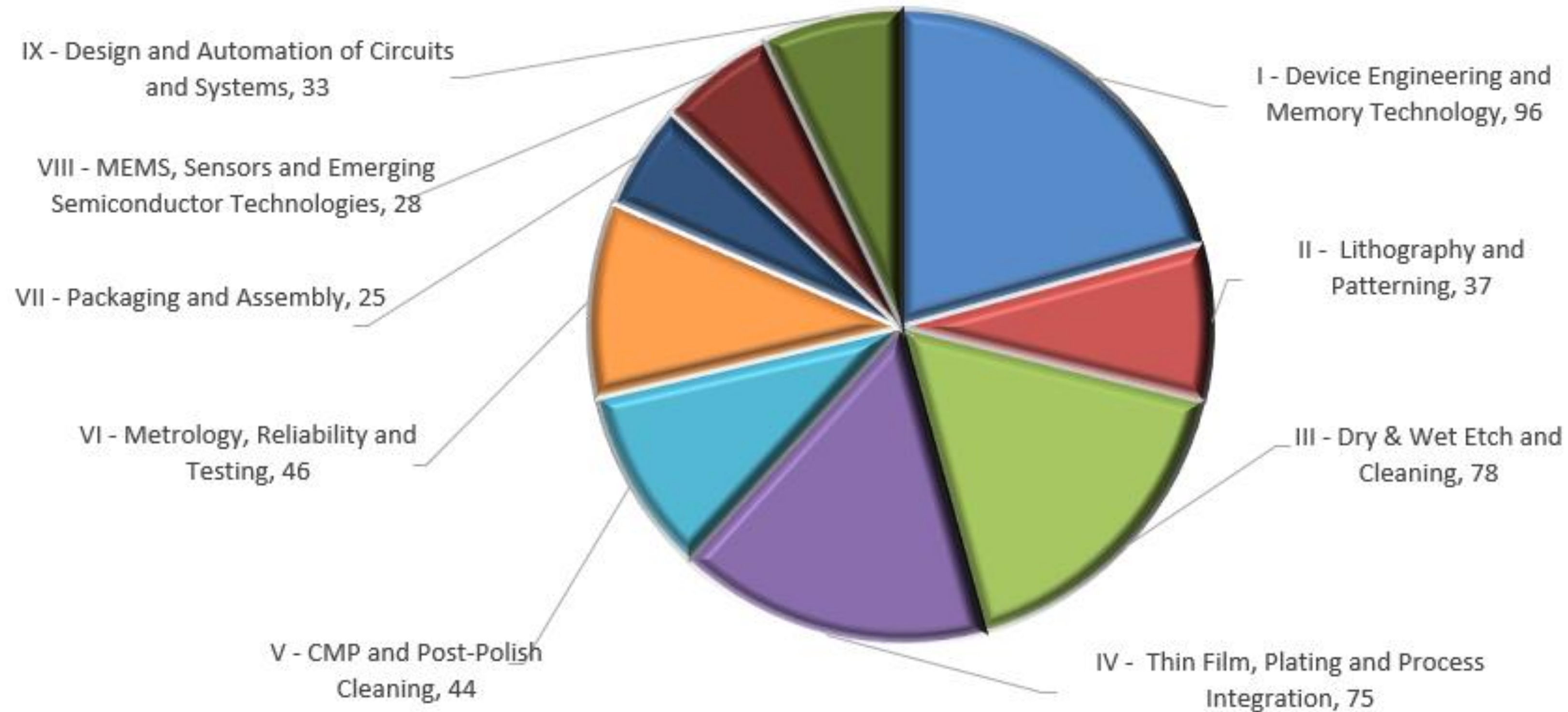


# MS Teams Live Meeting and SEMI Cloud





# Record High 462 submissions from 9 Symposiums





# International Collaboration

845 registrations from 18 countries and regions

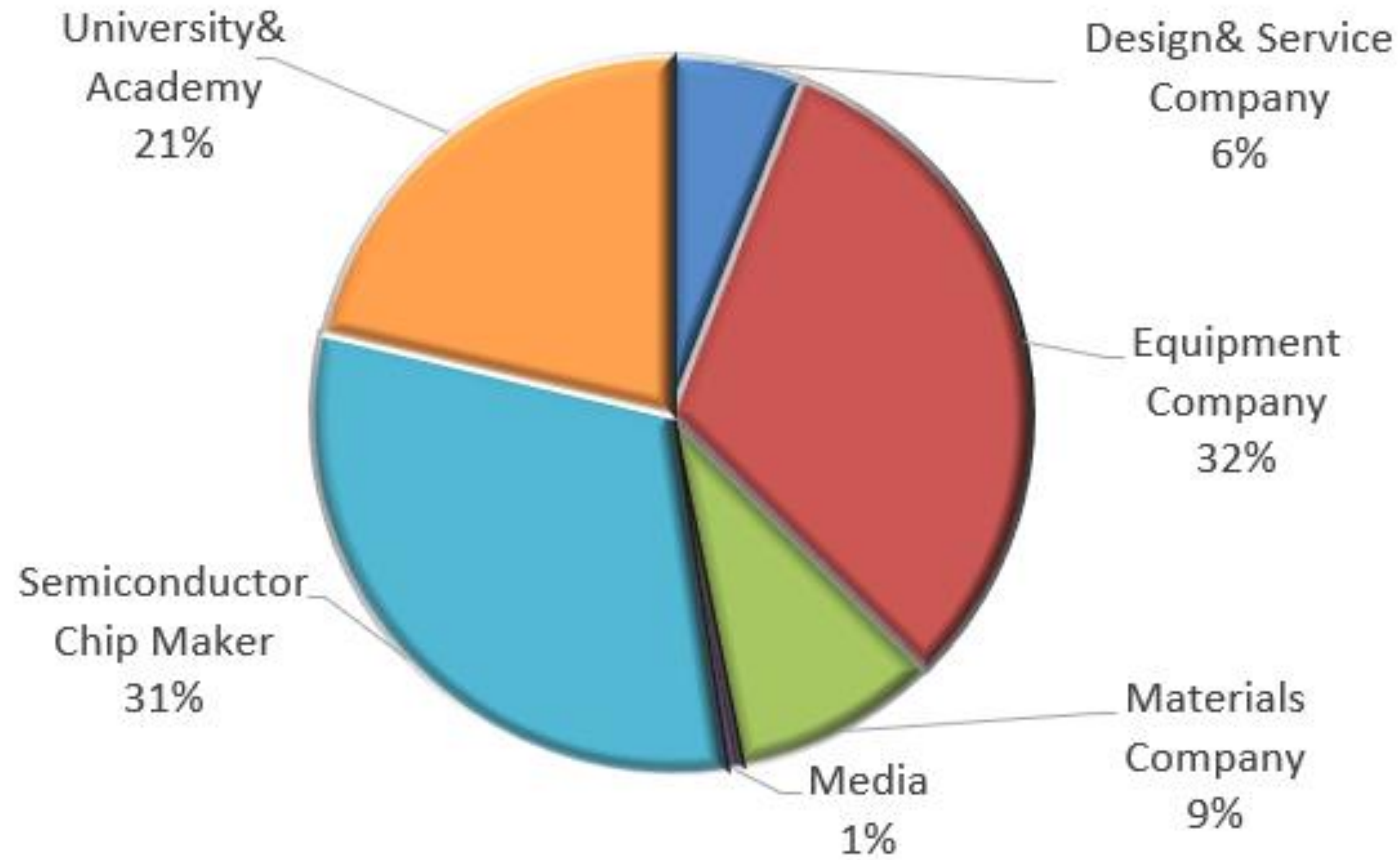


- Belgium
- China Hong Kong
- China Mainland
- China Taiwan Region
- Denmark
- France
- Germany
- Israel
- Japan
- Korea
- Malaysia
- Netherlands
- Saudi Arabia
- Singapore
- Sweden
- Switzerland
- United Kingdom
- United States of America



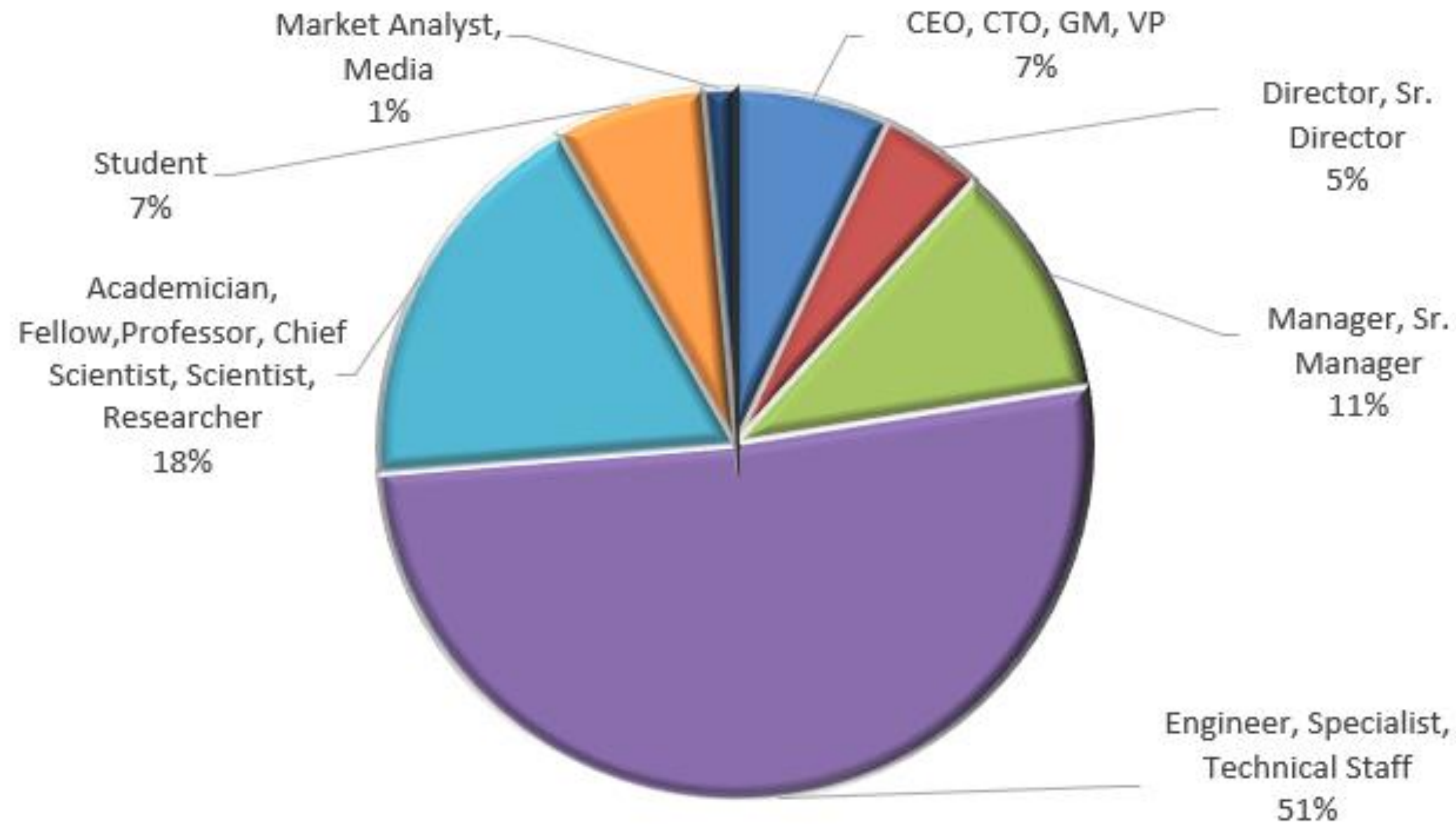


**845** registrations+**679** MS Teams Attendees+**55571** Page View  
**78%** registrations from the Industry





# 23% registrations from Industry Decision Makers







# Plenary Speakers



**Driving Moore's Law into the Next Decade**

**Dr. Martin van den Brink**  
President and Chief Technology Officer  
ASML



**Micro-Fabrication Equipment, the Foundation of Digital Revolution and Beyond**

**Dr. Gerald Yin**  
Chairman and CEO  
AMEC



**Advanced 3D Chiplet Packaging Technology and Manufacturing**

**Dr. Marvin Liao**  
Vice President, APTS  
TSMC



**An Innovative 3D HITOC 4F<sup>2</sup> DRAM Architecture**

**Dr. Feng Hong**  
CEO  
ICLeague Technology



# 9 Symposia with 100 Invited Speakers

Symp I: Device Engineering and Memory Technology

Symp. II: Lithography and Patterning

Symp. III: Dry & Wet Etch and Cleaning

Symp. IV: Thin Film, Plating and Process Integration

Symp. V: CMP and Post-Polish Cleaning

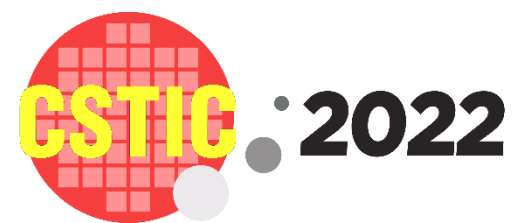
Symp. VI: Metrology, Reliability and Testing

Symp. VII: Packaging and Assembly

Symp. VIII: MEMS, Sensors and Emerging Semiconductor Technologies

Symp. IX: Design and Automation of Circuits and Systems

**Virtual Conference: June 14-July 12** [v.semi.org.cn/cstic](http://v.semi.org.cn/cstic)





# WFD Training Course



2017 - present  
 Dean /Professor  
 Electronics Engineering Department, North China University of Technology

2009 – 2017  
 Professor at Institute of Microelectronics of Chinese Academy of Sciences  
 Research for 14nm FDSOI and 22nm bulk technology

July'99 –July'09  
 Infineon Technologies (East Fishkill, NY, USA)  
 Process Engineer / Project manager







# >180 Participating Companies

3M  
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 ASM  
 ASML  
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 Axcelis  
 Baker Hughes  
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 Beijing Normal University  
 Beijing Superstring Academy of Memory Technology  
 Beijing University of Posts and Telecommunications  
 Beijing University Of Technology  
 Berkeley  
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 Cambridge University  
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 Guyingsu Technology  
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 Hanyang University  
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 Huahai New Materials  
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 Jiangyin high tech Zone Investment Promotion Bureau  
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 King Abdullah University of Science & Technology  
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# >180 Participating Companies

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 Mingqi Consulting  
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 Nissan Chem  
 North China University of Technology  
 Nouryon  
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 Onto Innovation  
 Osaka Vacuum  
 Peking University

Photonics  
 Piotech  
 Politecnico Di Milano  
 Proximus  
 Rainbow Material  
 Repro  
 Ruixinku International  
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 SGS Semiconductor  
 Shanghai ICRD  
 Shanghai Industrial Technology Research Institutes  
 Shanghai Jiaotong University  
 Shanghai Micro Electronics Equipment  
 Shanghai Tech University  
 Shanghai University  
 Shanghai University of Technology  
 Shinhao Materials  
 SHPP (Shanghai)  
 Sinyang  
 Sky Semiconductor  
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 SMIC Shanghai  
 SMNC  
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 Xilinx  
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 XMC Wuhan  
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 Zeiss  
 Zhejiang University  
 ZJU-Hangzhou Global Scientific and Technological Innovation Center  
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Conference Chair



**Dr. Beichao Zhang**  
Conference Executive  
Co-Chair



**Prof. Ru Huang**  
Conference Co-Chair



**Prof. Cor Claeys**  
Conference Co-Chair



**Dr. Steve X. Liang**  
Conference Co-Chair



**Dr. Qinghuang Lin**  
Conference Co-Chair





# Symposium Chairs



Dr. Ru Huang  
**Chair, S-I**  
Peking Univ.  
China



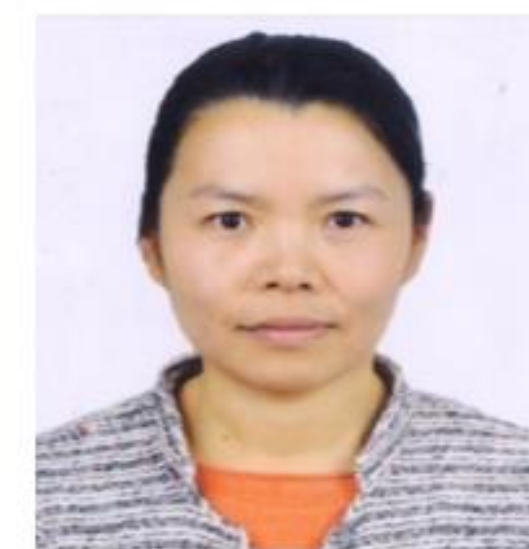
Dr. Leo Pang  
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Dr. Beichao Zhang  
**Chair, S-IV**  
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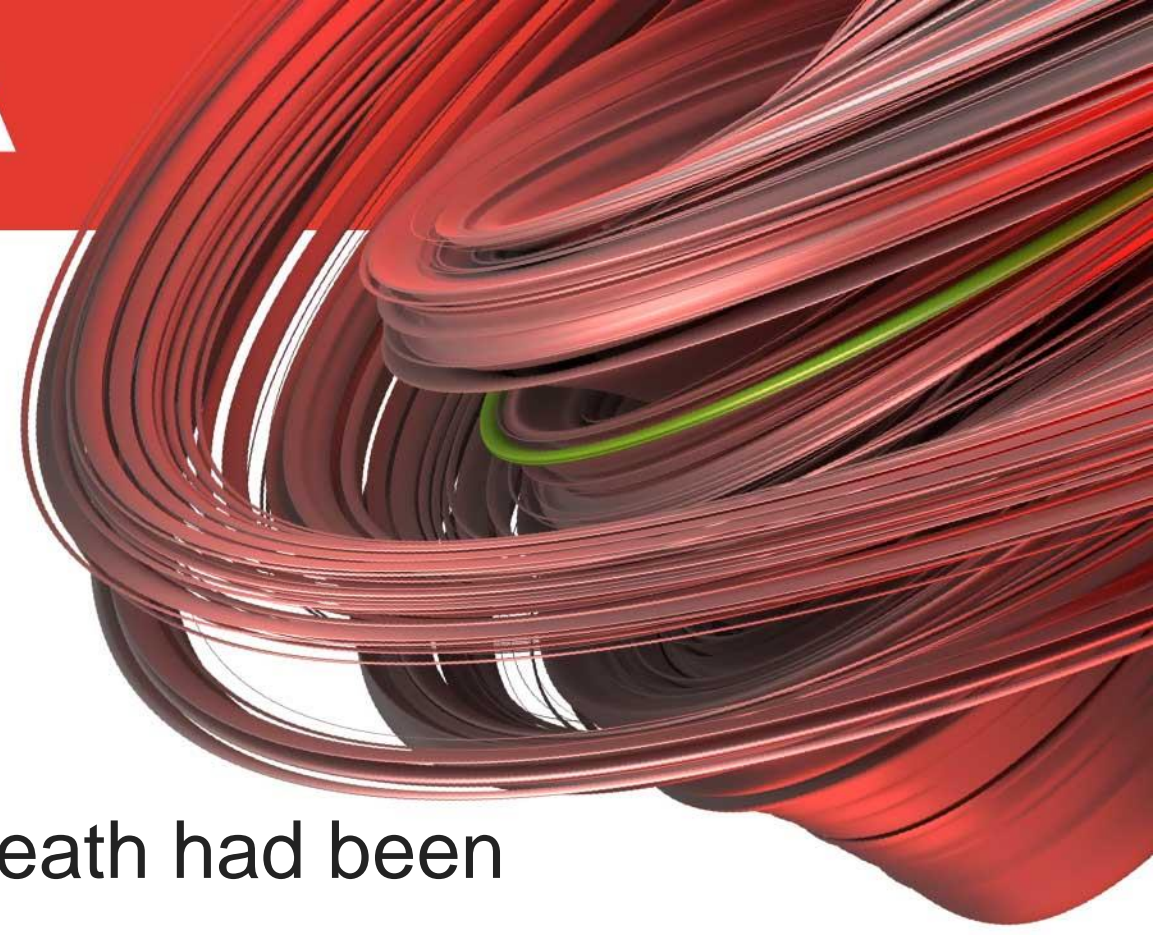


Dr. Zhuo Cheng  
**Chair S-IX**  
Zhejiang Univ.  
China



Dr. Hsiang-Lan Lung  
**Chair Poster**  
Macronix, Taiwan,  
China





# COVID-19 Plague in Shanghai

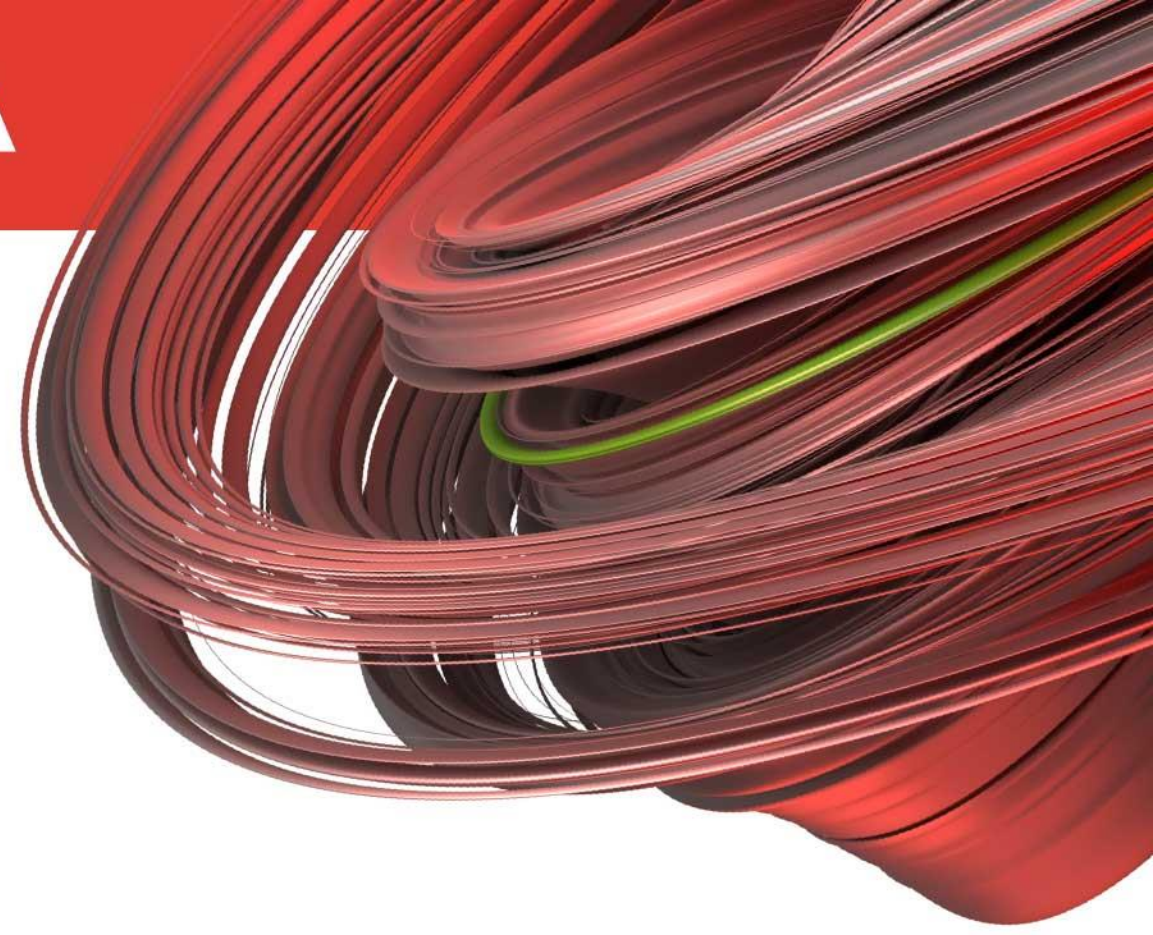
- More than 600,000 positive patients or asymptomatic patients had been confirmed, while 588 death had been certified by government during April and May in Shanghai.
- Committees and SEMI China president had to make the decision to transfer to virtual conference in late April.
- By combining MS Teams live meeting and SEMI cloud website, CSTIC 2022 has successfully overcome all the difficulties brought by COVID-19. Speakers and attendees have communicated quite well and **great result have been achieved.**



Source: Baidu







# Special Thanks to Sponsors and Co-organizers

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# CSTIC 2023

**Time: March 20 ~ 21, 2023**

**Venue: Shanghai International Convention Center(SHICC)**

**Call for Papers Deadline: Nov. 1, 2022**





Thank you!